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DATE: 16 August, 2024

PCN #: 2691

PCN Title: Additional Wafer Sources and Transfer of Wafer Manufacturing Site for Select Discrete Products

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of notification by contacting your local Diodes sales representative. If you require samples for evaluation purposes, please submit a corresponding request within 30 days as well. Otherwise, samples may not be built prior to the implementation of the announced change(s).

The change(s) announced in this PCN will not be implemented prior to the target implementation date, i.e. 90 days from the stated notification date, unless Diodes receives written customer approval before that date.

Previously agreed upon customer specific product and/or process change requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



**PRODUCT CHANGE NOTICE**

**PCN-2691-REV1**

| Notification Date:   | Implementation Date: | Product Family:        | Change Type:  | PCN #:      |
|--|----------------------|------------------------|---|-------------|
| 16 August, 2024  | 14 November, 2024    | Discrete Semiconductor | Additional Wafer Source, Wafer Diameter, Metallization System, Wire Bond Material | <b>2691</b> |
| <b>TITLE</b>   |                      |                        |   |             |
| Additional Wafer Sources and Transfer of Wafer Manufacturing Site for Select Discrete Products   |                      |                        |   |             |
| <b>DESCRIPTION OF CHANGE</b>   |                      |                        |   |             |
| <p>This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes Incorporated has qualified the following wafer source changes for select discrete products listed below.</p> <ul style="list-style-type: none"><li>• Diodes internal wafer fabrication source (JKFAB) in Hsinchu, Taiwan as additional wafer source, and Diodes internal assembly and test site (SAT) located in Shanghai, China and Diodes internal assembly and test site (CAT) located in Chengdu, China for processing wafer back metal (BM).</li><li>• Diodes internal wafer fabrication source (SFAB2) in Shanghai, China as additional wafer source with wafer top metal (TM) and back metal (BM) being processed at Diodes internal CAT site. Wafer top metal will be changed from TiNiAg to NiAu at CAT.</li><li>• Diodes internal wafer fabrication source WX1 in WuXi, China as new wafer source. Affected products will be transferred from Diodes internal wafer fabrication source SSEC in Shanghai, China, which is planned to be closed by 31 August 2024.</li><li>• Diodes external wafer fabrication source Yea Shin Technology Co., Ltd. in Keelung, Taiwan, manufacture of 6-inch diameter wafers with a standardized metal system (back metal composition) in addition to the currently qualified 4-inch diameter wafers.</li><li>• Diodes external wafer fabrication source Phenitex Semiconductor Corporation (PTS) 1<sup>st</sup> FAB in Okayama, Japan as additional wafer source using Au bond wire at Diodes internal SAT site.</li></ul> <p>Full electrical characterization and reliability testing have been completed on representative part numbers to ensure there is no change to product reliability, device functionality or electrical specifications in the datasheet.</p> <p>There will be no change to the Form, Fit, or Function of affected products.</p> |                      |                        |   |             |
| <b>IMPACT</b>  |                      |                        |   |             |
| No change in datasheet parameters  |                      |                        |   |             |
| <b>PRODUCTS AFFECTED</b>   |                      |                        |   |             |
| Table 1 – Affected part list to add JKFAB as additional wafer source, and add SAT and CAT for BM<br>Table 2 – Affected part list to add SFAB2 as additional wafer source, and add CAT for TM and BM<br>Table 3 – Affected part list to transfer to WX1 FAB as new wafer source<br>Table 4 – Affected part list to add Yea Shin 6-inch diameter wafer as additional wafer source<br>Table 5 – Affected part list to add PTS 1st FAB as additional wafer source using Au bond wire at SAT  |                      |                        |   |             |

| WEB LINKS  |   |
|--|---|
| Manufacturer's Notice:   | <a href="https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/">https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/</a> |
| For More Information Contact:  | <a href="https://www.diodes.com/about/contact-us/contact-sales/">https://www.diodes.com/about/contact-us/contact-sales/</a>   |
| Data Sheet:  | <a href="https://www.diodes.com/catalog/">https://www.diodes.com/catalog/</a>   |
| DISCLAIMER   |   |
| Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days from the notification date of this PCN, all changes described in this announcement are considered approved. |   |

| Table 1 - Affected part list to add JK FAB as additional wafer source, and add SAT and CAT for BM |                 |            |                |                 |                 |
|---|-----------------|------------|----------------|-----------------|-----------------|
| BC53-16PA-7   | BCX5216TA       | D3Z30BF-7  | DDZ9713T-7     | FZT953TA        | MMBZ5258BW-7-F  |
| BC807-16-7-F  | BCX5216TC       | D3Z33BF-7  | DDZ9714T-7     | FZT955TA        | MMBZ5259BS-7-F  |
| BC807-16W-7   | BCX52TA         | D3Z36BF-7  | DDZ9715T-7     | MJD32C-13       | MMBZ5259BT-7-F  |
| BC807-25-7-F  | BCX5316-13R     | DDZ28-7    | DDZ9716T-7     | MMBTA55-7-F     | MMBZ5259BTS-7-F |
| BC807-25W-7   | BCX5316TA       | DDZ30ASF-7 | DDZ9717T-7     | MMBTA56-7-F     | MMBZ5259BW-7-F  |
| BC807-40-13-F   | BCX5316TC       | DDZ30BSF-7 | DDZX36-7       | MMBZ5255BS-7-F  | MMDT4413-7-F    |
| BC807-40-7-F  | BCX53TA         | DDZ30CSF-7 | DMB2227A-7     | MMBZ5255BT-7-F  | MMSTA55-7-F     |
| BC807-40W-7   | BCX53TC         | DDZ30DS-7  | DPLS350E-13    | MMBZ5255BTS-7-F | MMSTA56-7-F     |
| BCM846BS-7  | BZT52C43-7-F-79 | DDZ30DSF-7 | DPLS350Y-13    | MMBZ5255BW-7-F  | MMSZ5255B-7-F   |
| BCM847BS-7  | BZX84C30S-7-F   | DDZ33ASF-7 | DPLS350YTC     | MMBZ5256BS-7-F  | MMSZ5255BS-7-F  |
| BCP5116TA   | BZX84C30T-7-F   | DDZ33BSF-7 | DT955-7        | MMBZ5256BT-7-F  | MMSZ5256B-13-F  |
| BCP5116TC   | BZX84C30W-7-F   | DDZ33CSF-7 | DXT2222A-13    | MMBZ5256BTS-7-F | MMSZ5256B-7-F   |
| BCP51TA   | BZX84C33S-7-F   | DDZ33DSF-7 | DXT2907A-13    | MMBZ5256BW-7-F  | MMSZ5256BS-7-F  |
| BCP5216TA   | BZX84C33T-7-F   | DDZ34-7    | DXT3906-13     | MMBZ5257BS-7-F  | MMSZ5257B-7-F   |
| BCP52TA   | BZX84C33W-7-F   | DDZ36ASF-7 | DXTP06080BFG-7 | MMBZ5257BT-7-F  | MMSZ5257BS-7-F  |
| BCP5316TA   | BZX84C36S-7-F   | DDZ36BSF-7 | DXTP07100BFG-7 | MMBZ5257BTS-7-F | MMSZ5258B-7-F   |
| BCP5316TC   | BZX84C36T-7-F   | DDZ36CSF-7 | DZDH0401DW-7   | MMBZ5257BW-7-F  | MMSZ5258BS-7-F  |
| BCP53TA   | BZX84C36W-7-F   | DDZ36DSF-7 | FZT753TA       | MMBZ5258BS-7-F  | MMSZ5259B-7-F   |
| BCX5116TA   | BZX84C39S-7-F   | DDZ39ASF-7 | FZT753TC       | MMBZ5258BT-7-F  | MMSZ5259BS-7-F  |
| BCX5116TC   | BZX84C39T-7-F   | DDZ39BSF-7 | FZT792ATA      | MMBZ5258BTS-7-F | ZXT953KTC       |
| BCX51TA   | BZX84C39W-7-F   | DDZ39CSF-7 |                |                 |                 |

| Table 2 - Affected part list to add SFAB2 as additional wafer source, and add CAT for TM and BM |               |               |               |              |  |
|---|---------------|---------------|---------------|--------------|--|
| SBR140S1F-7   | SBR1U150SA-13 | SBR2A150SA-13 | SBR2U150SA-13 | SBR3150SB-13 |  |

**Table 3 - Affected part list to transfer to WX1 FAB as new wafer source**

|            |                |            |            |            |            |
|------------|----------------|------------|------------|------------|------------|
| 1N4933G-T  | KBP4T10        | RABS20M    | RS1J-13-F  | RS2G-13-F  | RS3G-13-F  |
| 1N4934G-T  | MRS30M         | RABS20M-13 | RS1JB-13-F | RS2GA-13-F | RS3GB_HF   |
| 1N4935G_HF | MRS30M-13      | RH02-T     | RS1K-13-F  | RS2J_HF    | RS3GB-13-F |
| 1N4935G-T  | MSB30TM        | RH04-T     | RS1KB-13-F | RS2J-13-F  | RS3J_HF    |
| 1N4937G-T  | PR1004G_HF     | RH06-T     | RS1KP1M-7  | RS2JA-13-F | RS3J-13-F  |
| ABS10TM    | PR1004G_HF-A52 | RKBP410    | RS1M_HF    | RS2K-13-F  | RS3JB-13-F |
| ABS20T1M   | PR1005G_HF     | RKBP410-LS | RS1M-13-F  | RS2M_HF    | RS3K_HF    |
| ABS20TM    | PR1005G-T      | RS1A-13-F  | RS1MB-13-F | RS2M-13-F  | RS3K-13-F  |
| FRS1JE     | PR1006G_HF     | RS1AB-13-F | RS1MEWF-7  | RS2MA_HF   | RS3KB-13-F |
| FRS1JE-7   | PR1006G-T      | RS1B-13-F  | RS1MSWFM-7 | RS2MA-13-F | RS3M-13-F  |
| FRS1MD_HF  | PR1007G_HF     | RS1BB-13-F | RS2A-13-F  | RS3A-13-F  | RS3MB_HF   |
| FRS1ME     | PR1007G_HF-A52 | RS1D-13-F  | RS2AA-13-F | RS3AB-13-F | RS3MB-13-F |
| FRS1ME-13  | PR1007G-T      | RS1DB-13-F | RS2B-13-F  | RS3B-13-F  | RS5KP5M-13 |
| FRS1ME-7   | PR1505G_HF     | RS1G_HF    | RS2BA-13-F | RS3BB-13-F | RTT410     |
| FRS3MB_HF  | PR2006G_HF-A52 | RS1G-13-F  | RS2D-13-F  | RS3D-13-F  | RTT410-13  |
| FS1MED-7   | PR2007G_HF     | RS1GB-13-F | RS2DA-13-F | RS3DB-13-F | TT4TM      |
| FS2MED_HF  | PR3007G_HF     | RS1J_HF    | RS2G_HF    | RS3G_HF    | TT8T08-13  |
| FS2MED-7   |                |            |            |            |            |

**Table 4 - Affected part list to add Yea Shin 6-inch diameter wafer as additional wafer source**

|              |               |                |               |           |          |
|--------------|---------------|----------------|---------------|-----------|----------|
| DTH8E06D     | FES1JD_HF     | LTTH806SDFW    | MUR460D       | SF20JG_HF | STPR1030 |
| DTH8E06FP    | LTTH806EFW    | LTTH806SDFW_NC | MUR460D_FR    | SF30GG_HF | STPR2020 |
| DTH8R06D     | LTTH806RDW    | LTTH806SDW_NC  | MUR460-T      | SF30JG_HF | STPR2030 |
| DTH8R06D1-13 | LTTH806RFW    | MUR120-T       | SF10DG_HF     | SF40DG_HF | STPS1020 |
| DTH8R06FP    | LTTH806RFW_NC | MUR140-T       | SF10GG_HF-A52 | SF50JG_HF | STPS1620 |
| DTH8S06D     | LTTH806RW     | MUR460_E       | SF20DG_HF     | STPF1030  | STPS2020 |
| DTH8S06FP    | LTTH806SDF    | MUR460-A52     | SF20GG_HF     | STPR1020  |          |

**Table 5 - Affected part list to add PTS 1st FAB as additional wafer source using Au bond wire at SAT**

|               |               |                |                |                |                |
|---------------|---------------|----------------|----------------|----------------|----------------|
| BZT52HC10WF-7 | BZT52HC18WF-7 | BZT52HC2V4WF-7 | BZT52HC39WF-7  | BZT52HC43WF-7  | BZT52HC6V2WF-7 |
| BZT52HC11WF-7 | BZT52HC20WF-7 | BZT52HC2V7WF-7 | BZT52HC3V0WF-7 | BZT52HC4V3WF-7 | BZT52HC6V8WF-7 |
| BZT52HC12WF-7 | BZT52HC22WF-7 | BZT52HC30WF-7  | BZT52HC3V3WF-7 | BZT52HC4V7WF-7 | BZT52HC7V5WF-7 |
| BZT52HC13WF-7 | BZT52HC24WF-7 | BZT52HC33WF-7  | BZT52HC3V6WF-7 | BZT52HC5V1WF-7 | BZT52HC8V2WF-7 |
| BZT52HC15WF-7 | BZT52HC27WF-7 | BZT52HC36WF-7  | BZT52HC3V9WF-7 | BZT52HC5V6WF-7 | BZT52HC9V1WF-7 |
| BZT52HC16WF-7 |               |                |                |                |                |

Note: Change wire bond material from Cu to Au at SAT for the parts listed in Table 5